CLAIMS

1. A sputtering target, comprising:

(1) Fe, (2) Pt, (3) one or more elements selected from Ag, Au, B, Co, Cr, Cu, Ga, Ge, Mn, Mo, Nb, Ni, Pd, Re, Rh, Ru, Si, Sn, Ta, W, V, and Zn, and (4) the balance, wherein

an atomic ratio of the (1) Fe to the (2) Pt is 34 to 55 at%,

a total concentration of the (1) Fe and the (2) Pt is 50 mol % or more,

a content of the elements in (3) is 0.5 to 15 mol% in total,

a remainder of (4) is an oxide which may selectively contain impurities, a volume ratio of the oxide is 40 vol.% or more, and

an average particle area (average size) of an oxide phase calculated using ImageJ with a SEM image at a field magnification of 3000 times is 4.0 μm^2 or less.

2. The sputtering target according to claim 1, wherein

a bending strength is 300 MPa or more.

3. The sputtering target according to claim 1, wherein

the oxide contains an oxide of Si.

4. The sputtering target according to claim 3, wherein

the oxide further contains one or more oxides of elements selected from Al, B, Ba, Be, Ca, Ce, Cr, Dy, Er, Eu, Ga, Gd, Ho, Li, Mg, Mn, Nb, Nd, Pr, Sc, Sm, Sr, Ta, Tb, Ti, V, Y, Zn, and Zr.

5. A sputtering target assembly comprising:

the sputtering target according to any one of claims 1 to 4 and

a backing plate bonded to the sputtering target.